

Evaluates: MAX22211

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MAX22211 Evaluation Kit

General Description

The MAX22211 evaluation kit (EV kit) provides a proven design to evaluate the +36V, 3.8A Dual H-Bridge MAX22211 motor driver. The MAX22211 can drive two brushed DC motors or a single stepper motor. The MAX22211 IC integrates very low impedance FETs in a dual H-Bridge configuration with a typical RON (highside + low-side) of 0.25Ω . The EV kit features headers, test points, and terminal blocks to provide an interface to the MAX22211 motor driver. The MAX22211 integrated current-sense output ISENA and ISENB can be monitored using test points or can be connected to an external ADC using header J4. The MAX22211 features embedded current-drive regulation (CDR) with adjustable chopping current (ITRIP). The MAX22211 EV kit operates from an input voltage of +4.5V to +36V (V_M). An on board +3.3V regulator U2 (MAX6765TTSD2+) provides a regulated +3.3V to drive the MAX22211 logic inputs. Terminal blocks J1 and J6 are installed to provide an interface for the high voltage, high current V_M inputs, and motor driver outputs OUT A and OUT B.

Features

- Easy Evaluation of the MAX22211
- Configurable Current-Drive Regulation
- On-board +3.3V Regulator to Drive MAX22211 Logic Inputs
- Test Points and Headers to Interface with MAX22211 Logic Inputs and Current-Sense Outputs
- Fully Assembled and Tested
- Proven PCB Layout

Ordering Information appears at end of data sheet.



MAX22211 EV Kit Board Photo

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Quick Start

Required Equipment

- MAX22211 EV kit
- +36V DC, 3.8A power supply
- 100kHz square-wave generator (optional)
- Brushed DC motor or load

Procedure

The EV kit is fully assembled and tested. Use the following steps to verify board operation:

- As with all motor drive applications, stopping or braking the motor can cause a back EMF (BEMF) current and voltage spike. At high supply voltages (+36V), this can cause the supply to rise above the absolute maximum allowable voltage to the supply pins of a motor drive IC. It is highly recommended that the power supply be clamped appropriately to avoid damage to the motor driver IC.
- 2) Verify that shunts are installed in the default position.
- 3) Connect a +36V supply to the V_M and adjust the V_M voltage to the desired operating voltage.
- Adjust the I_{TRIP} chopping current according to the position of shunts on headers J2 and J3 to accommodate the load requirement.
- 5) Apply a PWM signal to the DIN1_/DIN2_ inputs as desired to drive the load. For example, a +3.3V to 0V, 20kHz PWM signal with a 20% duty cycle can be used to drive a brushed DC motor connected to output A. To drive a load with current flowing from OUT2A to OUT1A, DIN1A would be driven to logic LOW (GND), and the PWM signal would be applied to DIN2A.

Detailed Description of Hardware

Enable Controls

The MAX22211 enable pins (ENA and ENB) are controlled by installing shunts on headers J13 and J14, or the pins can be connected to a microcontroller using header J4.

On-Board +3.3V Control

The MAX22211 features an on-board +3.3V LDO that operates from +4.5V to +36V. The input voltage to the LDO is supplied by the V_M voltage. To provide 3.3V to the MAX22211 logic pins from the LDO, install a shunt in position 2–3 of header J18. An external +3.3V supply can be used, which can be connected to TP3, and in this case, a shunt should be installed in positions 1–2 of header J18.

PWM Controls

Each MAX22211 H-Bridge can be individually PWM controlled by two logic inputs (DIN1_, DIN2_) applied to either headers J4 or J9 to J12, or test points TP7 to TP10. Table 1 below describes the behavior of the full H-Bridge output pins OUT1_ and OUT2_ with respect to the input signals EN, DIN1_, and DIN2_. PWM techniques can be used to control the output duty cycle and implement motor speed control.

Current Regulation Controls

The MAX22211 features embedded current-drive regulation (CDR). The bridge current is sensed by a non-dissipative integrated current-sensing circuit (ICS), and it is then compared with the threshold current (I_{TRIP}). As soon as the bridge current exceeds the threshold, the device enforces the decay for a fixed OFF-time (t_{OFF}). Once t_{OFF} has elapsed, the driver is re-enabled for the next PWM cycle.

The chopping current threshold (I_{TRIP}) can be configured by connecting a resistor between the REF_ pins and GND. The MAX22211 EV kit has two 20k Ω resistors installed in series from each of the REF_ pins (R3 and R5 for REFA, and R4 and R6 for REFB) to GND. Shunts can be installed on headers J2 or J3 to short one of the 20k Ω series resistors to reduce the resistance from each REF_ pin to GND from 40k Ω to 20k Ω .

The following equation describes the relationship between I_{TRIP} and R_{REF} , where $K_I = 36$ KV when the Half-Full-Scale input level (HFS) is logic low and 18.4kV when HFS is logic high.

$$I_{\text{TRIP}} = \frac{K_{|}(KV)}{R_{\text{REF}}(K\Omega)}$$

Table 1. Full Bridge EN_, DIN1_, DIN2_, OUT1_, OUT2_ Truth Table

EN_	DIN1_	DIN2_	OUT1_	OUT2_	DESCRIPTION
0	Х	Х	High-Z	High-Z	H-bridge disabled. High impedance (High-Z)
1	0	0	L	L	Brake Low; Slow decay
1	1	0	Н	L	Reverse (Current from OUT1_ to OUT2_)
1	0	1	L	Н	Forward (Current from OUT2_ to OUT1_)
1	1	1	Н	Н	Brake High; Slow decay

Using headers J2 and J3 and resistors R3-R6, the ITRIP current for each H-Bridge can be configured to 0.9A or 1.8A.

Other ITRIP current levels can be obtained by mounting different resistors in place of R3, R4, R5, and R6. Refer to the MAX22211 IC data sheet for the RRFF resistor range. Table 2 describes the relationship between ITRIP and the header J2 and J3 shunt positions.

Current-Sense Output (CSO)

Currents proportional to the internally sensed motor current are output to pins ISENA and ISENB for the H-bridge A and B, respectively. The current is sensed when one of the two low-side FETs sinks the output current, and it is, therefore, meaningful both during the energizing (t_{ON}) phase and during the slow-decay phase (brake). In fast decay and during the blanking time, the current is not monitored, and the ISEN outputs are a zero current. The following equation shows the relationship between the current sourced at ISEN and the output current.

$$I_{\rm ISEN}(A) = \frac{I_{\rm OUT}(A)}{K_{\rm ISEN}}$$

KISEN represents the current scaling factor between the output current and its replica at pin ISEN. KISEN is typically 7500A/A when HFS is logic low and 3840A/A when HFS is logic high. For instance, if the instantaneous output current is 1.8A and HFS is logic low. The current sourced at ISEN is 240µA. By connecting an external signal resistor

Table 2. I_{TRIP} Chopping Current Control

(RISEN) between ISEN_ and GND, a voltage proportional to the motor current is generated. The EV kit is shipped with 3kΩ resistors (R7 and R8) installed from ISENA and ISENB to GND.

CDR Open-Drain Outputs

The CDRA and CDRB pins are active-low open-drain outputs, which are asserted during the fixed decay time interval (t_{OFF}) enforced by the current-drive regulation loop. In this way, the external controller can monitor whether the integrated current loop has taken control of the driver overwriting the status of the PWM logic inputs (DIN1 and DIN2). The CDR signal can be used by the external controller for a variety of reasons and provides information about the actual load during current regulation. The CDRA and CDRB pins on the MAX22211 EV kit have a $1k\Omega$ pullup to +3.3V installed. The CDRA and CDRB pins can be monitored either using pins 4 and 5 of header J5, or test points TP13 and TP14.

Decay Mode Controls

Two logic input pins allow the user to set the decay mode during tOFF. The MAX22211 supports slow, fast, and mixed-decay mode. The decay mode can be controlled by driving the DECAY2 and DECAY1 pins to GND or +3.3V. Table 3 describes the decay mode truth table and the behavior of the DECAY_ headers (DECAY1 and DECAY2) on the MAX22211 EV kit.

HEADER	SHUNT POSITION	R_{REF} VALUE (k Ω)	OUTPUT CHOPPING CURRENT I _{TRIP} (A)	
10	Not Installed	40	Output A chopping current set to 0.9A when HFS is logic low, 0.45A when HFS is logic high.	
JZ	1–2	20	Output A chopping current set to 1.8A when HFS is logic low, 0.9A when HFS is logic high.	
10	Not Installed	40	Output B chopping current set to 0.9A when HFS is logic low, 0.45A when HFS is logic high.	
53	1–2	20	Output B chopping current set to 1.8A when HFS is logic low, 0.9A when HFS is logic high.	

Table 3. Decay Mode

DECAY2	DECAY1	DECAY MODE
0	0	Slow
0	1	Mixed 30% Fast/70% Slow
1	0	Mixed 60% Fast/40% Slow
1	1	Fast

Default Header Position

The following table describes the default position of the headers to operate the MAX22211 EV kit as described in the *Quick Start Procedure* section.

HEADER	SHUNT POSITION	DESCRIPTION	
J2	Not Installed	Output A chopping current set to 0.9A	
	1–2*	Output A chopping current set to 1.8A	
J3	Not Installed	Output B chopping current set to 0.9A	
	1–2*	Output B chopping current set to 1.8A	
10	Not Installed*	ITRIP scaling at 100%	
J8	1–2	I _{TRIP} scaling at 50%	
J13	Not Installed	Output A disabled	
	1–2*	Output A enabled	
J14	Not Installed	Output B disabled	
	1–2*	Output B enabled	
147	1–2*	Connects the SLEEP pin to V _M to wake the part	
JT7	2–3	Connects the SLEEP pin to GND to put the part in low power mode	
11.0	1–2	+3.3V supplied externally	
510	2–3*	+3.3V supplied using on-board LDO	

Table 4. Default Header Position

*Indicates default position

Ordering Information

PART	ТҮРЕ
MAX22211EVKIT#	EV Kit

#Denotes RoHS compliance.

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MAX22211 EV Kit Bill of Materials

ITEM	REF_DES	QTY	MFG PART #	MANUFACTURER	VALUE	DESCRIPTION
1	C1, C3	2	CL05A105KO5NNN	SAMSUNG	1UF	CAP; SMT (0402); 1UF; 10%; 16V; X5R; CERAMIC
2	C2	1	CGA3E2X7R2A223K080AA	TDK	0.022UF	CAP; SMT (0603); 0.022UF; 10%; 100V; X7R; CERAMIC
3	C4, C5	2	C3216C0G2A104J160	TDK	0.1UF	CAP; SMT (1206); 0.1UF; 5%; 100V; C0G; CERAMIC
4	C6	1	EEE-FK2A470AQ	PANASONIC	47UF	CAP; SMT (CASE_H13); 47UF; 20%; 100V; ALUMINUM-ELECTROLYTIC
5	C7	1	C0805C224K1RAC; GRM21AR72A224KAC5	KEMET; MURATA	0.22UF	CAP; SMT (0805); 0.22UF; 10%; 100V; X7R; CERAMIC
6	C8	1	GRM21BR70J106K; C2012X7R0J106K125AB; CGA4J1X7R0J106K125AC	MURATA; TDK;TDK	10UF	CAP; SMT (0805); 10UF; 10%; 6.3V; X7R; CERAMIC
7	C9	1	C1608X7S2A104K080AB	TDK	0.1UF	CAP; SMT (0603); 0.1UF; 10%; 100V; X7S; CERAMIC
8	D1	1	SML-P11UTT86	ROHM	SML-P11UTT86	DIODE; LED; SMT; PIV=1.8V; IF=0.02A
9	J1	1	1727010	PHOENIX CONTACT	1727010	CONNECTOR; FEMALE; THROUGH HOLE; GREEN TERMINAL BLOCK; RIGHT ANGLE; 2PINS
10	J2, J3, J8-J16	11	PCC02SAAN	SULLINS	PCC02SAAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT THROUGH; 2PINS; -65 DEGC TO +125 DEGC
11	J4	1	PPPC101LFBN-RC	SULLINS ELECTRONICS CORP.	PPPC101LFBN-RC	CONNECTOR; FEMALE; THROUGH HOLE; HEADER CONNECTOR; STRAIGHT; 10PINS
12	J5	1	90120-0128	MOLEX	90120-0128	CONNECTOR; THROUGH HOLE; C-GRID III SINGLE ROW STRAIGHT PIN HEADER; STRAIGHT THROUGH; 8PINS
13	J6	1	OSTVN04A150	ON-SHORE TECHNOLOGY INC	OSTVN04A150	CONNECTOR; TERMINAL BLOCK; FEMALE; THROUGH HOLE; STRAIGHT; 4PINS
14	J7	1	PBC04SAAN	SULLINS ELECTRONICS CORP.	PBC04SAAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 4PINS; -65 DEGC TO +125 DEGC
15	J17, J18	2	PBC03SAAN	SULLINS	PBC03SAAN	CONNECTOR; MALE; THROUGH HOLE; BREAKAWAY; STRAIGHT; 3PINS; -65 DEGC TO +125 DEGC
16	R1	1	CRCW04021K40FK; RC0402FR-071K4L	VISHAY DALE; YAGEO PHICOMP	1.4K	RES; SMT (0402); 1.4K; 1%; +/-100PPM/DEGC; 0.0630W
17	R3-R6	4	ERA-2AEB203	PANASONIC	20K	RES; SMT (0402); 20K; 0.10%; +/-25PPM/DEGC; 0.0630W
18	R7, R8	2	CRCW04023K00FK	VISHAY DALE	ЗК	RES; SMT (0402); 3K; 1%; +/-100PPM/DEGC; 0.0630W
19	R10, R11	2	RC0402FR-071KL; MCR01MZPF1001	YAGEO; ROHM SEMICONDUCTOR	1К	RES; SMT (0402); 1K; 1%; +/-100PPM/DEGC; 0.0630W
20	SPACER1—SPACER4	4	9032	KEYSTONE	9032	MACHINE FABRICATED; ROUND-THRU HOLE SPACER; NO THREAD; M3.5; 5/8IN; NYLON
21	TP1, TP3	2	5010	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; RED; PHOSPHOR BRONZE WIRE SIL;
22	TP2, TP4, TP11	3	5011	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; BLACK; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
23	TP5-TP10, TP12-TP16	11	5014	KEYSTONE	N/A	TEST POINT; PIN DIA=0.125IN; TOTAL LENGTH=0.445IN; BOARD HOLE=0.063IN; YELLOW; PHOSPHOR BRONZE WIRE SILVER PLATE FINISH;
24	U1	1	MAX22211_TQFN	MAXIM	MAX22211_TQFN	EVKIT PART - IC; MAX22211; 36V; 3.8A TWO H-BRIDGE FOR DUAL BRUSHED OR SINGLE STEPPER MOTOR DRIVE; PACKAGE OUTLINE DRAWING: 21-0140; PACKAGE LAND PATTERN: 90-0013; TQFN32-EP
25	U2	1	MAX6765TTSD2+	MAXIM	MAX6765TTSD2+	IC; VREG; AUTOMOTIVE MICROPOWER LINEAR REGULATOR WITH SUPERVISOR; TDFN6-EP
26	PCB	1	MAX22211	MAXIM	PCB	PCB:MAX22211
27	R12, R13	0	N/A	N/A	OPEN	RESISTOR; 0603; OPEN; FORMFACTOR
TOTAL		60				

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MAX22211 EV Kit Schematic Diagram

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MAX22211 EV Kit PCB Layouts



MAX22211 EV Kit—Silkscreen Top Layer



MAX22211 EV Kit—Top Layer

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MAX22211 EV Kit PCB Layouts (continued)

MAX22211 EV Kit—Layer 2



MAX22211 EV Kit—Layer 3



MAX22211 EV Kit PCB Layouts (continued)

MAX22211 EV Kit—Bottom Layer

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Revision History

REVISION	REVISION	DESCRIPTION	PAGES
NUMBER	DATE		CHANGED
0	4/23	Initial release	—



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